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IN THE CLAIMS:

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1. (original) A method of wiring formation comprising the steps of:
forming a feeder film partially on a substrate;
forming on the substrate a plating base film such that the plating base film partially overlaps the feeder film;
forming a plated wiring on the plating base film; and
selectively removing at least a portion of the feeder film that is exposed from the plated wiring.
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2. (original) A method of wiring formation according to Claim 1, wherein the step of forming on the substrate a plating base film is performed using a physical film making process.
 3. (original) A method of wiring formation according to Claim 1, wherein the step of forming a plated wiring on the plating base film is performed using an electrolytic plating process.
 4. (original) A method of wiring formation according to Claim 1, wherein the step of selectively removing at least a portion of the feeder film that is exposed from the plated wiring is performed using a wet etching process.
 5. (original) A method of wiring formation according to Claim 1, wherein a width of a portion of the plating base film that is stacked on the feeder film is wider than the smallest wire width of the feeder film.
 6. (original) A method of wiring formation according to Claim 1, wherein the plating base film comprises at least one of an adhesive layer and a diffusion preventive layer.

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7. (original) A method of wiring formation comprising the steps of:
forming a feeder film partially on a substrate;
forming on the substrate a resist pattern which has an opening defining a wiring forming area, such that a portion of the feeder film is exposed from the opening in the resist pattern;
forming a plating base film at least on the substrate in the opening;
forming a plated wiring on the plating base film in the opening;
removing the resist pattern; and
selectively removing at least a portion of the feeder film that is exposed from the plated wiring.
8. (original) A method of wiring formation according to Claim 7, wherein the step of forming on the substrate a plating base film is performed using a physical film making process.
9. (original) A method of wiring formation according to Claim 7, wherein the step of forming a plated wiring on the plating base film is performed using an electrolytic plating process.
10. (original) A method of wiring formation according to Claim 7, wherein the step of selectively removing at least a portion of the feeder film that is exposed from the plated wiring is performed using a wet etching process.
11. (original) A method of wiring formation according to Claim 7, wherein a width of a portion of the plating base film that is stacked on the feeder film is wider than the smallest wire width of the feeder film.

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12. (original) A method of wiring formation according to Claim 7, wherein the plating base film comprises at least one of an adhesive layer and a diffusion preventive layer.

13. (original) A method of manufacturing an electronic component comprising the steps of:

providing a substrate;
forming a feeder film partially on the substrate;
forming on the substrate a plating base film by using a physical film making process such that the plating base film partially overlaps the feeder film;
forming a plated wiring on the plating base film using an electrolytic plating process; and
selectively removing at least a portion of the feeder film that is exposed from the plated wiring, using a wet etching process.

14. (original) A method according to Claim 13, wherein a width of a portion of the plating base film that is stacked on the feeder film is wider than the smallest wire width of the feeder film.

15. (currently amended) A method according to Claim ~~13~~16, wherein a width of a portion of the plating base film that is stacked on the feeder film is wider than the smallest wire width of the feeder film.

16. (original) A method according to Claim 13, wherein the plating base film comprises at least one of an adhesive layer and a diffusion preventive layer.

17. (original) A method of manufacturing an electronic component comprising the steps of:

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providing a substrate;
forming a feeder film partially on a substrate;
forming on the substrate a resist pattern which has an opening defining a wiring forming area, such that a portion of the feeder film is exposed from the opening in the resist pattern;
forming a plating base film at least on the substrate in the opening using a physical film making process;
forming a plated wiring on the plating base film in the opening using an electrolytic plating process;
removing the resist pattern; and
selectively removing at least a portion of the feeder film that is exposed from the plated wiring, using a wet etching.

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18. (original) A method according to Claim 17, wherein a width of a portion of the plating base film that is stacked on the feeder film is wider than the smallest wire width of the feeder film.

19. (currently amended) A method according to Claim 17, wherein a width of a portion of the plating base film that is stacked on the feeder film is wider than the smallest wire width of the feeder film.

20. (original) A method according to Claim 17, wherein the plating base film comprises at least one of an adhesive layer and a diffusion preventive layer.

21. (new) A method according to Claim 1, wherein the plating base film comprises a diffusion preventive layer.

22. (new) A method according to Claim 7, wherein the plating base film

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comprises a diffusion preventive layer.

23. (new) A method according to Claim 13, wherein the plating base film comprises a diffusion preventive layer.

24. (new) A method according to Claim 17, wherein the plating base film comprises a diffusion preventive layer.

25. (new) A method according to Claim 1, further comprising a step of forming on the substrate a resist pattern having a reversed tapered shape.

26. (new) A method according to Claim 1, wherein the plating base film comprises an adhesive layer.